

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (currently amended): A system for ~~stacking~~ three-dimensional packaging of platelets, comprising in combination:

a slotted file; and

a plurality of platelets which fit into the slotted file wherein no pressure is required to hold the platelets within the slotted file.

Claim 2 (original): The system of Claim 1, wherein the slotted file has at least three walls.

Claim 3 (original): The system of Claim 2, wherein the at least three walls are composed of silicon.

Claim 4 (original): The system of Claim 2, wherein the slotted file has at least two side walls and at least one back wall.

Claim 5 (original): The system of Claim 4, wherein the at least two side walls have been etched with a plurality of grooves.

Claim 6 (original): The system of Claim 5, wherein a depth of the plurality of grooves is sufficient to hold each of the plurality of platelets.

Claim 7 (original): The system of Claim 5, wherein a spacing between the plurality of grooves is determined based on a platelet thickness.

Claim 8 (original): The system of Claim 5, wherein the spacing between the plurality of grooves is determined based on a number of platelets in a completed cube.

Claim 9 (original): The system of Claim 5, wherein the spacing between the plurality of grooves is determined based on an allocated space limitation.

Claim 10 (original): The system of Claim 4, wherein the at least one back wall is connected to an end of each of the at least two side walls to form a "U" shape.

Claim 11 (original): The system of Claim 10, wherein the plurality of grooves on the at least two side walls face directly across from each other.

Claim 12 (original): The system of Claim 1, wherein each of the plurality of platelets is comprised of a semiconductor chip placed into a chip carrier.

Claim 13 (original): The system of Claim 12, wherein the chip carrier has a floor and a frame.

Claim 14 (original): The system of Claim 13, wherein the floor and the frame are composed of a ceramic material.

Claim 15 (original): The system of Claim 13, wherein the floor protrudes past at least two edges of the frame forming flanges.

Claim 16 (original): The system of Claim 15, wherein the flanges fit into the plurality of grooves in the at least two side walls of the slotted file.

Claim 17 (original): The system of Claim 13, wherein the floor has a plurality of electrodes.

Claim 18 (original): The system of Claim 17, wherein the semiconductor chip is placed face down on the floor contacting the plurality of electrodes.

Claim 19 (canceled): The system of Claim 1, wherein epoxy is used to seal a completed cube.

Claim 20 (withdrawn): A method for stacking platelets, comprising in combination:
etching grooves into a wall material, wherein at least two side walls with a plurality of grooves and at least one back wall without the grooves is formed;
connecting the at least two side walls and the at least one back wall to form a slotted file; and
inserting a plurality of platelets into the slotted file forming a completed cube.

Claim 21 (withdrawn): The method of Claim 20, further comprising immersing the completed cube in epoxy.

Claim 22 (withdrawn): The method of Claim 20, wherein the wall material is silicon.

Claim 23 (withdrawn): The method of Claim 20, wherein a depth of the plurality of grooves is sufficient to hold each of the plurality of platelets.

Claim 24 (withdrawn): The method of Claim 20, wherein a spacing between the plurality of grooves is determined based on a platelet thickness.

Claim 25 (withdrawn): The method of Claim 20, wherein the spacing between the plurality of grooves is determined based on a number of platelets in the completed cube.

Claim 26 (withdrawn): The method of Claim 20, wherein the spacing between the plurality of grooves is determined based on an allocated space limitation.

Claim 27 (withdrawn): The method of Claim 20, wherein each of the plurality of platelets has at least two flanges that fit into the plurality of grooves.

Claim 28 (withdrawn). The method of Claim 20, wherein each of the plurality of platelets is comprised of a semiconductor chip placed into a chip carrier.

Claim 29 (canceled): A system for stacking platelets, comprising in combination:
a slotted file consisting of at least two side walls and at least one back wall, wherein the at least two side walls and the at least one back wall are composed of silicon, wherein the at least two side walls have been etched with a plurality of grooves, wherein the at least one back wall is connected to an end of each of the at least two side walls to form a "U" shape, and wherein the plurality of grooves on the at least two side walls face directly across from each other; and
a plurality of platelets, wherein each of the plurality of platelets is comprised of a semiconductor chip placed into a chip carrier, wherein the chip carrier has a floor and a frame, wherein the floor and the frame are composed of a ceramic material, wherein the floor protrudes past at least two edges of the frame forming flanges, wherein the flanges fit into the plurality of grooves in the at least two side walls of the slotted file, and wherein epoxy is used to seal a completed cube.